



FOR IMMEDIATE RELEASE

Contact: David Harrison, Director of Marketing
(408)542-5424

December 1, 2008

LOGIC Devices Introduces its Integrated Module Products family (IMOD)

Sunnyvale, CA – LOGIC Devices, Incorporated (NASDAQ: LOGC), a developer of high performance, low power integrated circuits; today announced its [Integrated Module products family \(IMOD\)](#). This family will facilitate the integration of LOGIC Devices' silicon IP as well as silicon IP from other semiconductor manufacturers, thereby, providing high density, wide-word memory arrays, sub-systems and systems in package.

The [IMOD family](#) is based on the integration of multiple silicon devices, manufactured on an organic laminate substrate and encapsulated with industry standard plastic encapsulating materials providing suitability of use in Industrial, Extended and Mil-Temp applications. This packaging technology provides a medium which offers customers significant board area savings, improved electrical characteristics such as lower capacitance, lower inductance, controlled impedance and excellent thermal properties, while minimizing manufacturing issues related to ultra fine pitch ball matrices and trace routability issues encountered with discrete component based solutions.

LOGIC's first [IMOD products](#) include high density memory arrays supporting the latest Double Data Rate, Synchronous DRAM (DDR3) architecture with backwards compatibility support for DDR2 and DDR1. These [IMOD memory products](#) are offered in either a 16mm x 22mm, 25mm² or a 25mm x 32mm laminate based BGA footprint. LOGIC Devices first DDR3 device is a 4.0 GB, 64 M x 64, DDR3-1333 DRAM available in industrial temperature grade (-40°C, +85°C) and packaged in a 16mm x 22mm, 271ball LPGA. These devices provides a 43% space savings over the use of (4) 96 ball, 9.15mm x 16.65mm BGAs as well as a 30% decrease in total I/O. Other targeted performance benchmarks include DDR3-1066 at extended temperature (-40°C, +105°C) and DDR3-800 at military temperature (-55°C, +125°C). Other IMOD family members currently in development include DDR1 and DDR2 product definitions in multiple density/organizations and packaged in one of the above mentioned package footprints.

LOGIC Devices' initial [IMOD product](#) members are targeted for Industrial, Embedded and Hi-Reliability markets with target applications including diagnostic imaging arrays, main-system (core) memory, high density - multi-port arrays, digital signal processor memory and high end data/video streaming servers. LOGIC Devices first [IMOD devices](#), available for purchase, will be two DDR1 devices, a 1.2Gb, 16M x 72/80 ([L9D112G80BG4](#)) as well as a 2.5Gb, 32M x 72/80 ([L9D125G80BG4](#)), both packaged in our 25mm², 219ball LPGA and available in three grades; Industrial, Extended and Mil-temp. LOGIC Devices' 2.5Gb ([L9D125G80BG4](#)) DDR1 will begin shipping in January 2009, initial Industrial pricing will be \$125.00 (qty. 1-100). Our DDR3 leadership product, packaged in our 16mm x 22mm-271ball LPGA is targeted for an April 2009 introduction.

LOGIC Devices Incorporated (NASDAQ: LOGC) an ISO9001:2000 registered corporation, is focused on developing high performance digital silicon and integrated product solutions for high performance, power sensitive applications. Our products meet or exceed the requirements for broadcast video, medical imaging, industrial-embedded computer, surveillance, and instrumentation as well as telecommunications companies. More information about LOGIC Devices and its' products are available at <http://www.logicdevices.com/>.

"Safe Harbor" Statement under the Private Securities Litigation Reform Act of 1995: Any statements in this press release regarding expectations of future events are "forward-looking statements" involving risks and uncertainties, including, but not limited to, market acceptance risks, the effect of economic conditions and shifts in supply and demand, the impact of competitive products and pricing, product development, commercialization and technological difficulties, availability of capital, and capacity and supply constraints. Please refer to the Management Discussion and Analysis of Financial Condition and Results of Operations (MD&A) for a discussion of risks in the most recent LOGIC Devices Annual Report on Form 10-K and the quarterly report under Form 10-Q.